

查询CP576供应商
PROCESS CP576
Power Transistor
PNP - Amp/Switch Transistor Chip

捷多邦，专业PCB打样工厂，24小时加急出货™

Central
Semiconductor Corp.

PROCESS DETAILS

Process	MULTI EPITAXIAL PLANAR
Die Size	203 x 227 MILS
Die Thickness	12.5 ± 1.0 MILS
Base Bonding Pad Area	38 x 76 MILS
Emitter Bonding Pad Area	47 x 72 MILS
Top Side Metalization	Al - 50,000Å
Back Side Metalization	Ag - 10,000Å

GEOMETRY



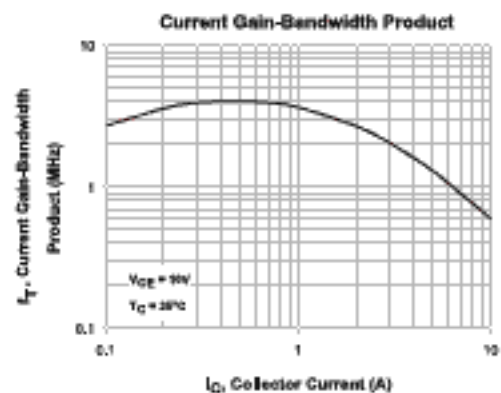
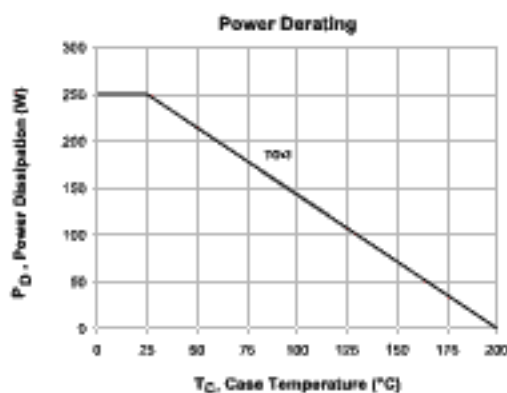
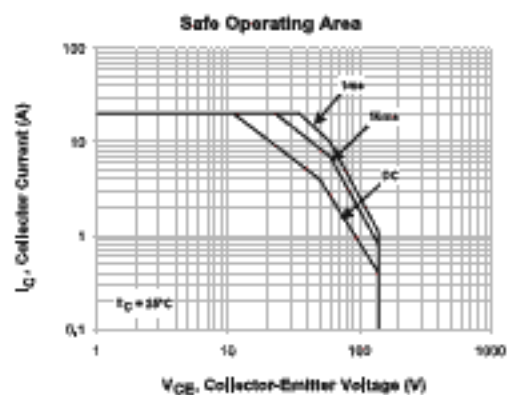
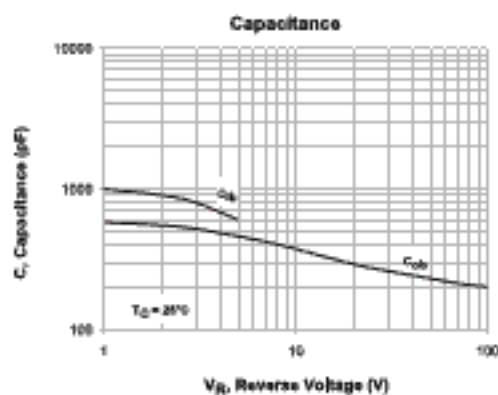
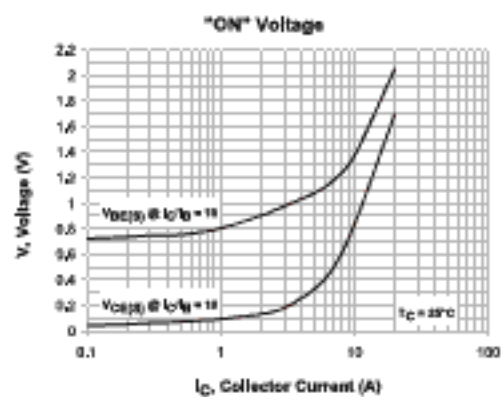
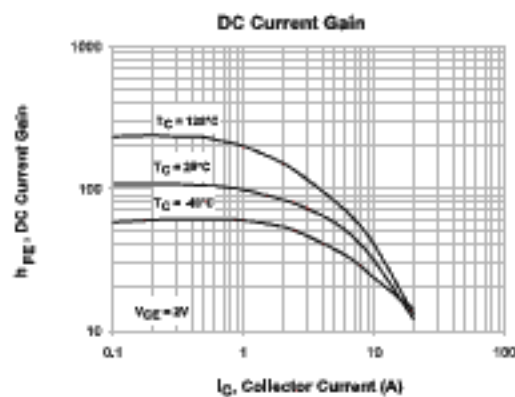
BACKSIDE COLLECTOR R0

GROSS DIE PER 4 INCH WAFER
240

PRINCIPAL DEVICE TYPES
MJ15004

145 Adams Avenue
Hauppauge, NY 11788 USA
Tel: (631) 435-1110
Fax: (631) 435-1824
www.centralsemi.com

R2 (1-August 2002)



145 Adams Avenue
Hauppauge, NY 11788 USA
Tel: (631) 435-1110
Fax: (631) 435-1824
www.centralsemi.com

R2 (1-August 2002)